

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3274735

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PETER A. GRUBER	08/12/2014
PAUL A. LAURO	08/18/2014
JAE-WOONG NAH	08/11/2014
RECEIVING PARTY DATA	
Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	New Orchard Road
City:	Armonk
State/Country:	NEW YORK
Postal Code:	10504
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14663754
CORRESPONDENCE DATA	
Fax Number:	(203)769-5706
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	203 433 3157
Email:	docket@oeklaw.com
Correspondent Name:	OTTERSTEDT, ELLENBOGEN & KAMMER, LLP
Address Line 1:	P.O. BOX 381
Address Line 4:	COS COB, CONNECTICUT 06807-0381
ATTORNEY DOCKET NUMBER:	YOR920120306US3
NAME OF SUBMITTER:	PAUL J. OTTERSTEDT
SIGNATURE:	/PAUL J. OTTERSTEDT/
DATE SIGNED:	03/20/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 6	
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IBM DOCKET NUMBER: YOR920120306US2

**DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN
APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT**

Title of Invention: **DOUBLE SOLDER BUMPS ON SUBSTRATES FOR LOW
TEMPERATURE FLIP CHIP BONDING**

As a below named inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

☒ United States application or PCT international application number 14467564
filed on 25-AUG-2014.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

Whereas, the undersigned inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document;

Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor ("ASSIGNOR") hereby sells or has sold, assigns or has assigned, and otherwise transfers or has transferred to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: **Peter A. Gruber**

Signature: Peter A. Gruber Date: 8/12/2014

(2) Legal Name of Inventor: **Paul A. Lauro**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Jae-Woong Nah**

Signature: _____ Date: _____

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(1) Legal Name of Inventor: **Peter A. Gruber**

Signature: _____ Date: _____

(2) Legal Name of Inventor: **Paul A. Lauro**

Signature:  _____ Date: 8/18/14

(3) Legal Name of Inventor: **Jac-Woong Nah**

Signature: _____ Date: _____

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Signature: _____ Date: _____

(2) Legal Name of Inventor: **Paul A. Lauro**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Jae-Woong Nah**

Signature: Jae-Woong Nah Date: 08/11/2014